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August 24-28, 2015. Ottawa, Canada.

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RE'15 offers an extensive program of interest to academia, government and industry including three distinguished keynote speakers and three conference days full of papers, panels, posters and demos. A series of exciting tutorials to develop skills in and advance awareness of requirements engineering practices is of particular interest to industry. The main conference is preceded by two days of workshops and the doctoral symposium.

CALL FOR CONTRIBUTIONS

RE'15 invites original submissions of **research papers**, **RE: Next! papers** and **industry papers** in all areas of requirements engineering including elicitation, specification, modeling, analysis, verification and evolution. Categories of **research papers** include Technical Solution papers that describe and validate better solutions to requirements problems, Scientific Evaluation papers that evaluate existing problem situations or proposed solutions by scientific means and Vision papers that explore successes and challenges of requirements practices, or present research roadmaps. **RE: Next!** papers are short communications that describe the current status of ongoing research. **Industry papers** report on the application of requirements engineering techniques in real-world settings, present problems or challenges encountered in practice and report on innovative approaches to requirements engineering practice in industrial or government settings. RE'15 also welcomes submissions for **workshops**, **tutorials**, **panels**, **interactive events**, **poster**, **tool demonstrations** and the **doctoral symposium**.

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JAN 26 WORKSHOP PROPOSALS
MAR 02 TUTORIAL PROPOSALS
MAR 02 PAPER ABSTRACTS
MAR 09 FULL PAPERS

APR 13 PANEL & INTERACTIVE PROPOSALS
APR 13 DOCTORAL SYMPOSIUM
APR 13 POSTERS & TOOL DEMOS
MAY 18 AUTHOR NOTIFICATION
JUN 19 CAMERA READY

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Section

